PCN Number:	20140609001	**PCN Date:**	06/09/2014

Title:	Qualification of Alternate Assembly site for select WCSP devices

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	09/09/2014	**Estimated Sample Availability:**	Provided upon Request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of JCAP as an alternate assembly site for the devices listed below. There is no material or dimensional differences between devices assembled at the 2 sites.

Reason for Change:

Continuity of Supply

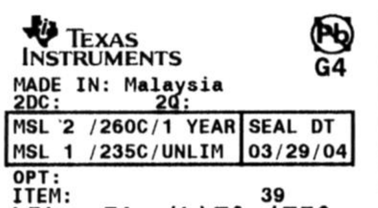
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
STATS ChipPAC (SCS)	Assembly Site Origin (22L)	ASO: STS
JCAP	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:
Assembly site code for STS= G
Assembly site code for JCP= P

Product Affected			
HPA02208YZPR	SN74AUP1T97YZPR	TPS22922BYFPR	TS5A22362YZPR
HPA02302YZPR	SN74AVC2T45YZTR	TS5A22364YZPR	

Reference Qualification Data: (Approved: April 2008)				
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.				
Qualification Device: TS3DS26227YZT (MSL 1-260C)				
Package / Die Attributes				
Assembly Site & Bump Site:	JCAP	Bump Composition:	SnAgCu	
# Pins-Designator, Family:	12-YZT, DSBGA	Bump Diameter:	0.225mm	
Passivation/Coating:	MA21009085			
Qualification: ☐ **Plan** ☒ **Test Results**				

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
**Steady-state Life Test	150C (168, 300 Hrs)	116/0	116/0	116/0
**High Temp. Storage Bake	170C (168, 420hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH/33.3 psia (96 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (500, 1000 Cyc)	77/0	77/0	77/0
Visual Mechanical	Per Manufacturing Specifications	Pass	Pass	Pass
Solderability	Steam age, 8 hours	Pass	Pass	Pass
Physical Dimensions	(per mechanical drawing)	Pass	Pass	Pass
Bump-shear	(per mfg. Site specification)	Pass	Pass	Pass
**Preconditioning: MSL1@260C				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com